

## SGM8601 1.1mA, 11MHz, Low Noise, Rail-to-Rail I/O Tiny Package, CMOS Operational Amplifier

### **GENERAL DESCRIPTION**

The SGM8601 is a single, low voltage, low noise and low power operational amplifier, which can operate from 2.1V to 5.5V single supply, while consuming only 1.1mA quiescent current at 5V.

The SGM8601 features a 4mV maximum input offset voltage. The minimum input common mode voltage is within 0.1V below the negative rail, and the output swing is rail-to-rail with heavy loads. It exhibits a high gain-bandwidth product of 11MHz and a slew rate of 8.5V/µs. These specifications make the operational amplifier appropriate for various applications.

The SGM8601 is available in a Green TDFN-2×2-8L package. It is specified over the extended -40°C to +125°C industrial temperature range.

## FEATURES

- Offset Voltage Range: 0mV to 4mV
- High Gain-Bandwidth Product: 11MHz
- High Slew Rate: 8.5V/µs
- Settling Time to 0.1% with 2V Step: 0.21µs
- Overload Recovery Time: 0.6µs
- Low Noise: 8.5nV/√Hz at 10kHz
- Rail-to-Rail Input and Output
- Supply Voltage Range: 2.1V to 5.5V
- Input Common Mode Voltage Range: -0.1V to 5.6V with V<sub>s</sub> = 5.5V
- Low Power: 1.1mA (TYP) Supply Current
- -40°C to +125°C Operating Temperature Range
- Available in a Green TDFN-2×2-8L Package

## **APPLICATIONS**

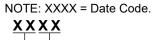
Sensors Audio Active Filters A/D Converters Communications Test Equipment Cellular and Cordless Phones Laptops and PDAs Photodiode Amplification Battery-Powered Instrumentation



### PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION	
SGM8601	TDFN-2×2-8L	-40℃ to +125℃	SGM8601XTDE8G/TR	8601 XXXX	Tape and Reel, 3000	

### MARKING INFORMATION



Date Code - Week Date Code - Year

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

### ABSOLUTE MAXIMUM RATINGS

Input Common Mode Voltage Range .....(-V<sub>S</sub>) - 0.3V to (+V<sub>S</sub>) + 0.3 Junction Temperature ......+150°C Storage Temperature Range .....--65°C to +150°C Lead Temperature (Soldering, 10s).....+260°C

ESD Susceptibility	
HBM	8000V
MM	400V
CDM	1000V

#### **RECOMMENDED OPERATING CONDITIONS**

Operating Temperature Range .....-40°C to +125°C

### **OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

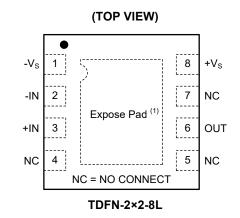
### ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

#### DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

## **PIN CONFIGURATION**



NOTE 1: Exposed pad can be connected to -V<sub>S</sub> or left floating.

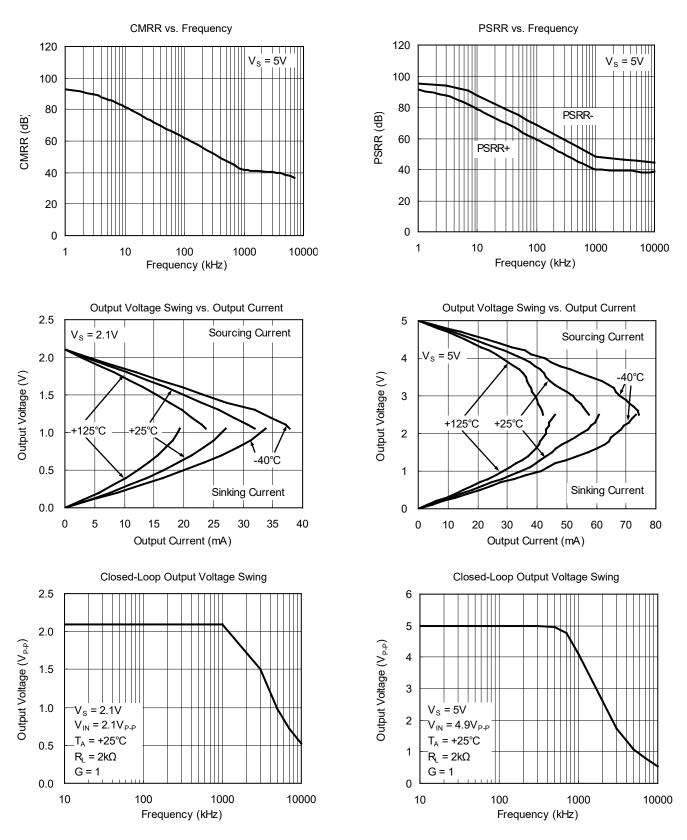


## **ELECTRICAL CHARACTERISTICS**

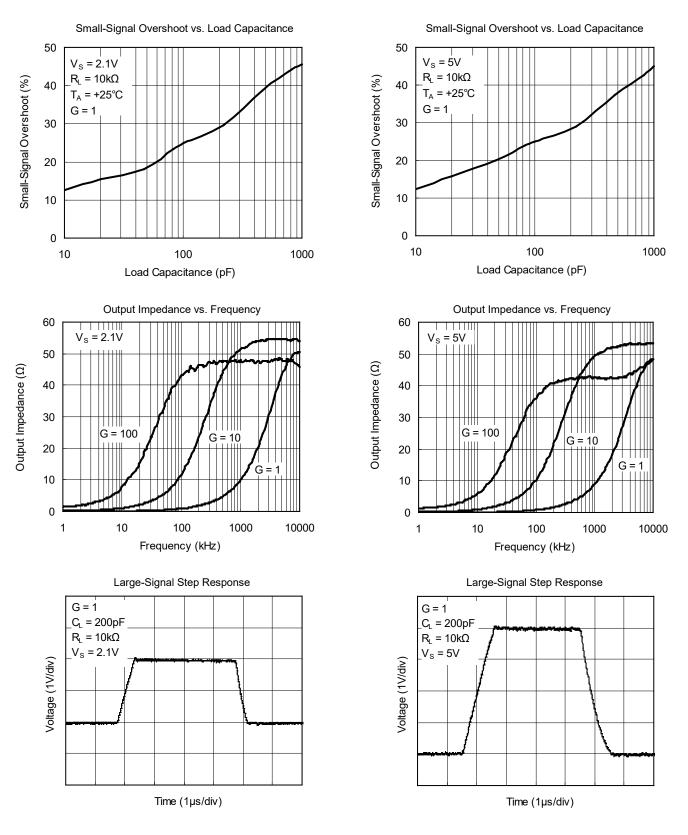
		SGM8601						
DADAMETED	CONDITIONS	TYP	MIN/MAX OVER TEMPERATURE					
PARAMEIER	CONDITIONS	+25℃	+25℃	-40℃ to +85℃	-40℃ to +125℃	UNITS	MIN/ MAX	
Input Characteristics								
Input Offect Voltage (V/)			0			mV	MIN	
input Onset voltage (vos)		2	4	4.5	5	mV	MAX	
Input Bias Current (I <sub>B</sub> )		1				pА	TYP	
Input Offset Current (Ios)		1				pА	TYP	
Input Common Mode Voltage Range (V_CM)	V <sub>S</sub> = 5.5V	-0.1 to +5.6				V	TYP	
Common Mode Rejection Potic (CMPR)	$V_{\rm S}$ = 5.5V, $V_{\rm CM}$ = -0.1V to 4V	82	67	66	65	dB	MIN	
	$V_{\rm S}$ = 5.5V, $V_{\rm CM}$ = -0.1V to 5.6V	70	59	58	57	to CUNITS MV MV pA pA V	MIN	
Open Leon Voltage Gain (A)	$R_L = 600\Omega$ , $V_{OUT} = 0.15V$ to 4.85V	92	84	74	65	dB	MIN	
	$R_L = 10k\Omega$ , $V_{OUT} = 0.05V$ to 4.95V	105	96	87	72	dB	MIN	
Input Offset Voltage Drift ( $\Delta V_{OS}/\Delta_T$ )		8.7				µv/°C	TYP	
Output Characteristics								
Output Voltage Swing from Reil	R <sub>L</sub> = 600Ω	76	90	110	135	mV	MAX	
Output voltage Swing norn Rail	R <sub>L</sub> = 10kΩ	7	11	13	18	mV	MAX	
Output Current (I <sub>OUT</sub> )		63	50	41	36	mA	MIN	
Closed-Loop Output Impedance	f = 1MHz, G = 1	8.5				Ω	TYP	
Power Supply								
		2.1	2.1	2.1	2.1	V	MIN	
Operating Voltage Range	$\begin{array}{ c c c c c c } \hline PARAMETER & CONDITIONS & +25^{\circ}C & +25^{\circ}C & -40^{\circ}C & to & +40^{\circ}\\ \hline +25^{\circ}C & +25^{\circ}C & -40^{\circ}C & to & +40^{\circ}\\ \hline +25^{\circ}C & +25^{\circ}C & -40^{\circ}C & to & +40^{\circ}\\ \hline +25^{\circ}C & +25^{\circ}C & -40^{\circ}C & to & +10^{\circ}\\ \hline \\ \hline \\ acteristics & & & & & & & & & & & & & & & & & & &$	5.5	V	MAX				
Power Supply Rejection Ratio (PSRR)		79	69	68	64	dB	MIN	
Quiescent Current ( $I_Q$ )	I <sub>OUT</sub> = 0	1.1	1.4	1.6	1.8	mA	MAX	
Dynamic Performance								
Gain-Bandwidth Product (GBP)	R <sub>L</sub> = 10kΩ	11				MHz	TYP	
Phase Margin ( $\phi_0$ )		62				o	TYP	
Full Power Bandwidth (BW <sub>P</sub> )	< 1% distortion	400				kHz	TYP	
Slew Rate (SR)	G = 1, 2V output step	8.5				V/µs	TYP	
Settling Time to 0.1% (t <sub>s</sub> )	G = 1, 2V output step	0.21				μs	TYP	
Overload Recovery Time	$V_{IN} \times G = V_S$	0.6				μs	TYP	
Noise Performance	•							
	f = 1kHz	12.5				nV/√Hz	TYP	
uiescent Current $(I_Q)$ ynamic Performance ain-Bandwidth Product (GBP) hase Margin ( $\phi_0$ ) ull Power Bandwidth (BW <sub>P</sub> ) lew Rate (SR) ettling Time to 0.1% (t <sub>S</sub> ) verload Recovery Time	f = 10kHz	8.5				nV/√Hz	TYP	



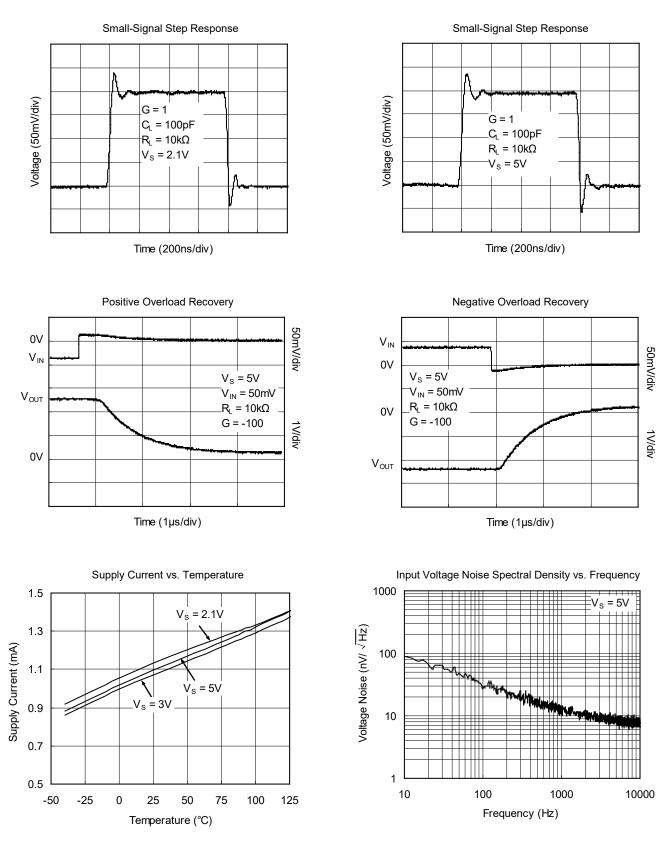
## **TYPICAL PERFORMANCE CHARACTERISTICS**



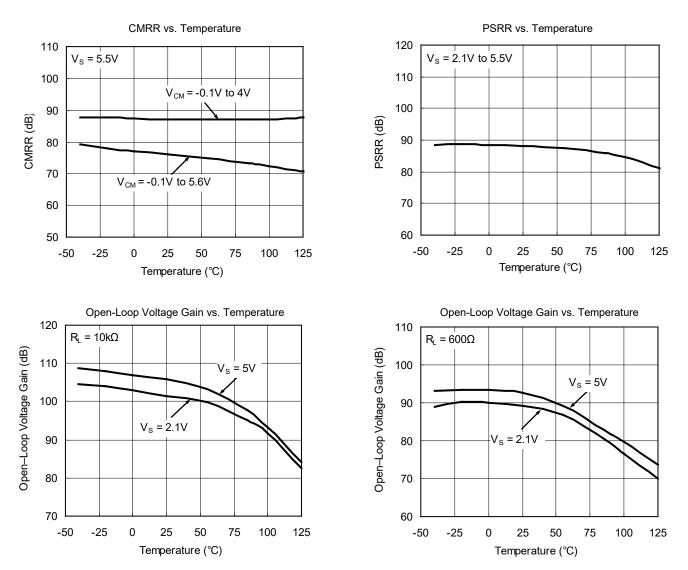
## **TYPICAL PERFORMANCE CHARACTERISTICS (continued)**



## **TYPICAL PERFORMANCE CHARACTERISTICS (continued)**



## **TYPICAL PERFORMANCE CHARACTERISTICS (continued)**



### **APPLICATION INFORMATION**

#### **Rail-to-Rail Input**

When SGM8601 works at the power supply between 2.1V and 5.5V, the input common mode voltage range is from  $(-V_S) - 0.1V$  to  $(+V_S) + 0.1V$ . In Figure 1, the ESD diodes between the inputs and the power supply rails will clamp the input voltage not to exceed the rails.

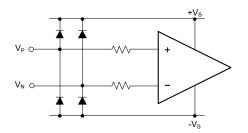


Figure 1. Input Equivalent Circuit

#### **Rail-to-Rail Output**

The SGM8601 supports rail-to-rail output operation. In single power supply application, for example, when +V<sub>S</sub> = 5V, -V<sub>S</sub> = GND,  $10k\Omega$  load resistor is tied from OUT pin to ground, the typical output swing range is from 0.007V to 4.993V.

#### **Driving Capacitive Loads**

The SGM8601 is designed for unity-gain stable for capacitive load up to 4700pF. If greater capacitive load must be driven in application, the circuit in Figure 2 can be used. In this circuit, the IR drop voltage generated by  $R_{\rm ISO}$  is compensated by feedback loop.

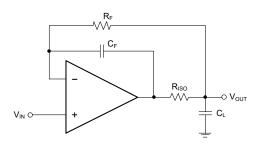


Figure 2. Circuit to Drive Heavy Capacitive Load

#### **Power Supply Decoupling and Layout**

A clean and low noise power supply is very important in amplifier circuit design, besides of input signal noise, the power supply is one of important source of noise to the amplifier through  $+V_s$  and  $-V_s$  pins. Power supply bypassing is an effective method to clear up the noise at power supply, and the low impedance path to ground of decoupling capacitor will bypass the noise to GND. In application,  $10\mu$ F ceramic capacitor paralleled with  $0.1\mu$ F or  $0.01\mu$ F ceramic capacitor is used in Figure 3. The ceramic capacitors should be placed as close as possible to  $+V_s$  and  $-V_s$  power supply pins.

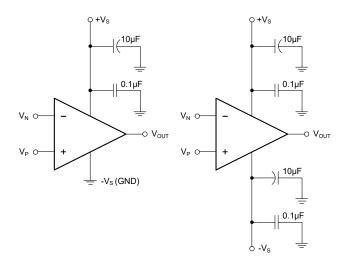


Figure 3. Amplifier Power Supply Bypassing

#### Grounding

In low speed application, one node grounding technique is the simplest and most effective method to eliminate the noise generated by grounding. In high speed application, the general method to eliminate noise is to use a complete ground plane technique, and the whole ground plane will help distribute heat and reduce EMI noise pickup.

#### Reduce Input-to-Output Coupling

To reduce the input-to-output coupling, the input traces must be placed as far away from the power supply or output traces as possible. The sensitive trace must not be placed in parallel with the noisy trace in same layer. They must be placed perpendicularly in different layers to reduce the crosstalk. These PCB layout techniques will help to reduce unwanted positive feedback and noise.



## **APPLICATION INFORMATION (continued)**

### **Typical Application Circuits**

#### **Difference Amplifier**

The circuit in Figure 4 is a design example of classical difference amplifier. If  $R_4/R_3 = R_2/R_1$ , then  $V_{OUT} = (V_P - V_N) \times R_2/R_1 + V_{REF}$ .

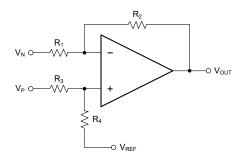


Figure 4. Difference Amplifier

#### High Input Impedance Difference Amplifier

The circuit in Figure 5 is a design example of high input impedance difference amplifier, the added amplifiers at the input are used to increase the input impedance and eliminate drawback of low input impedance in Figure 4.

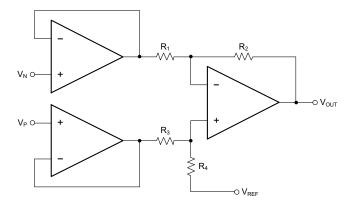


Figure 5. High Input Impedance Difference Amplifier

#### Active Low-Pass Filter

The circuit in Figure 6 is a design example of active low-pass filter, the DC gain is equal to  $-R_2/R_1$  and the -3dB corner frequency is equal to  $1/2\pi R_2C$ . In this design, the filter bandwidth must be less than the bandwidth of the amplifier, the resistor values must be selected as low as possible to reduce ringing or oscillation generated by the parasitic parameters in PCB layout.

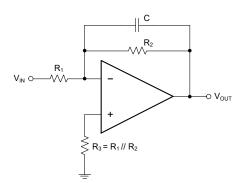


Figure 6. Active Low-Pass Filter

### **REVISION HISTORY**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

#### Changes from Original (SEPTEMBER 2015) to REV.A

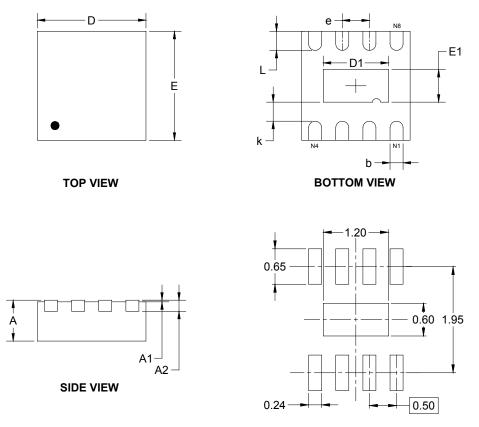
hanged from product preview to production data	All



Page

# PACKAGE OUTLINE DIMENSIONS

## TDFN-2×2-8L



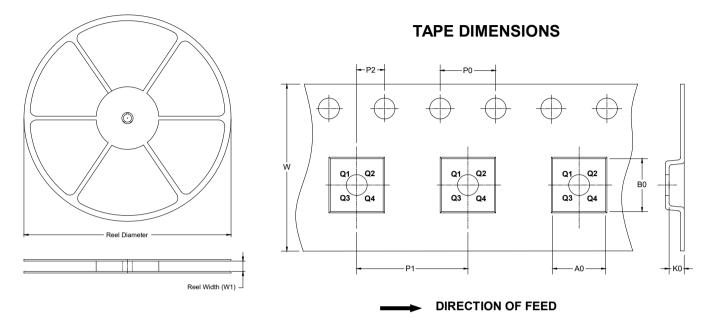
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol		nsions meters	Dimensions In Inches			
	MIN	MAX	MIN	MAX		
А	0.700 0.800		0.028	0.031		
A1	0.000	0.050	0.000	0.002		
A2	0.203	B REF	0.008 REF			
D	1.900	2.100	0.075	0.083		
D1	1.100	1.300	0.043 0.075 0.020	0.051		
E	1.900	2.100		0.083		
E1	0.500	0.700		0.028		
k	0.200 MIN		300.0	3 MIN		
b	0.180	0.300	0.007	0.012		
е	0.500 TYP		0.020	) TYP		
L	0.250	0.450	0.010	0.018		



## TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**

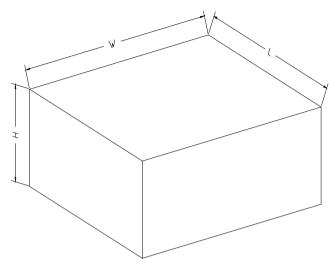


NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-2×2-8L	7″	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q1

### **CARTON BOX DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

### **KEY PARAMETER LIST OF CARTON BOX**

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton	]
7" (Option)	368	227	224	8	
7"	442	410	224	18	DD0002

